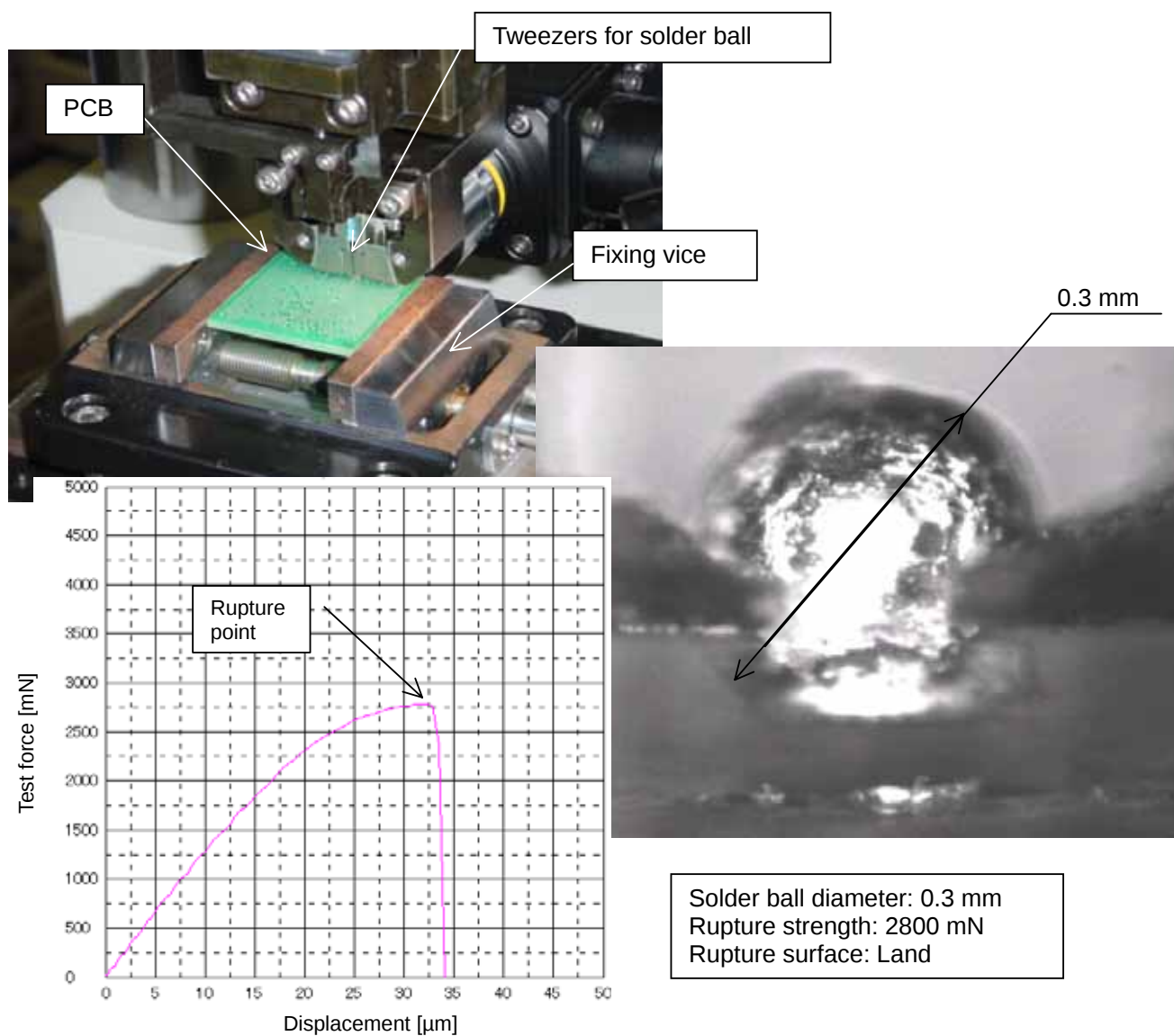


MST-I Application Information

Tensile Testing of Individual Solder Balls

Using solder ball tweezers, tensile tests can be carried out on a single solder ball.

Applicable standards: JEITA ET-7407



Optional Jigs

1. Tweezers for solder ball
2. Fixing vice
3. Stereomicroscope

Test Standard Summary

JEITA Standard

ET-7407 Environmental and endurance test methods for CSP/BGA package on mounting condition, Appendix 11 Evaluation board land peeling strength test

Test for evaluating the peeling strength of the land of a printed circuit board.

Test conditions

- Measurement accuracy of test force not specified
- Test speed 300 +/- 50 $\mu\text{m}/\text{sec}$
(18 +/- 3 mm/min)

Measurement items

- Rupture strength (maximum test force)
- Rupture mode (visually)

